

Description

Features

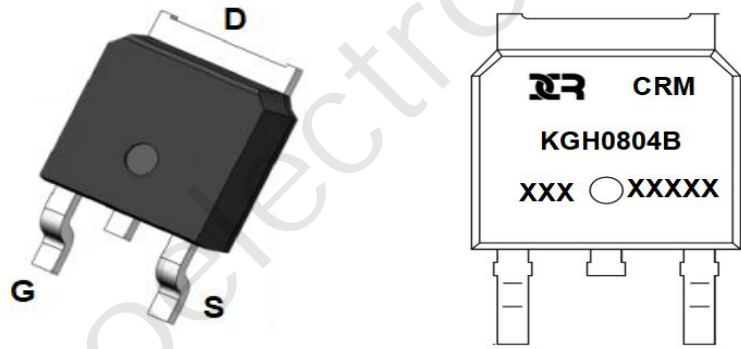
- 80V, 100A
 $R_{DS(ON)}$ Typ = 4.8mΩ @ $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKGH0804B	CRMKGH0804B	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	80	V	
V _{GS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _C = 25°C	100	A
		T _C = 100°C	60	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	400	A	
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	264	mJ	
P _D	Power Dissipation	T _C = 25°C	114	W
R _{θJC}	Thermal Resistance, Junction to Case	1.1	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	80	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	4.8	6.2	mΩ

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 40\text{V},$ $f = 1\text{MHz}$	-	3468	-	pF
C_{oss}	Output Capacitance		-	660	-	pF
C_{rss}	Reverse Transfer Capacitance		-	13	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 40\text{V}, I_D = 55\text{A}$	-	48	-	nC
Q_{gs}	Gate Source Charge		-	15	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	14	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 40\text{V}$ $I_D = 55\text{A}, R_{GEN} = 1.6\Omega$	-	16	-	ns
t_r	Turn-On Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	40	-	ns
t_f	Turn-Off Fall Time		-	12	-	ns

Drain-Source Diode Characteristics and Max Ratings

I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	100	A	
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	400	A	
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 20A	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F = 30A, di/dt = 100A/us	-	40	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	165	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 40\text{V}$, $V_G = 10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$, $I_{AS} = 32.5\text{A}$
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

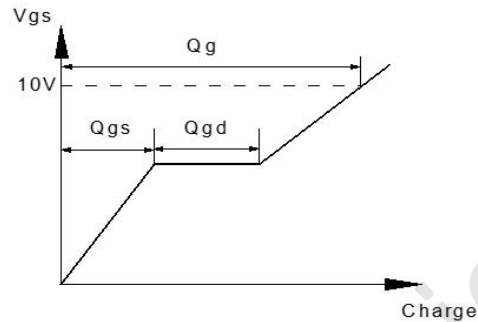


Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

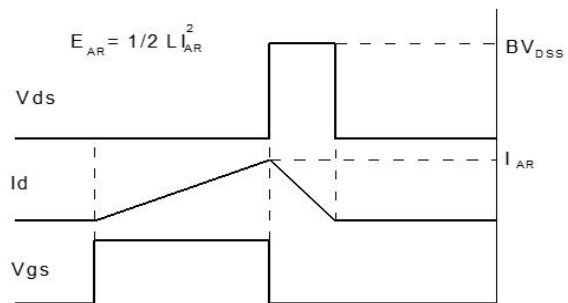
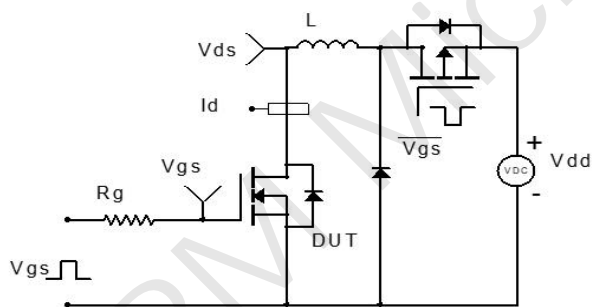


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

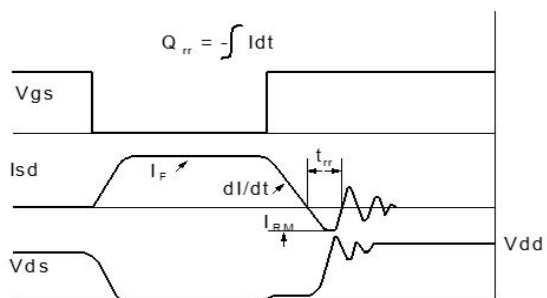
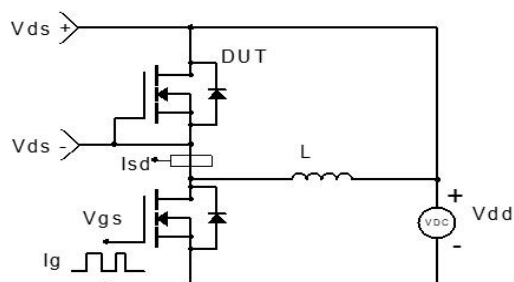
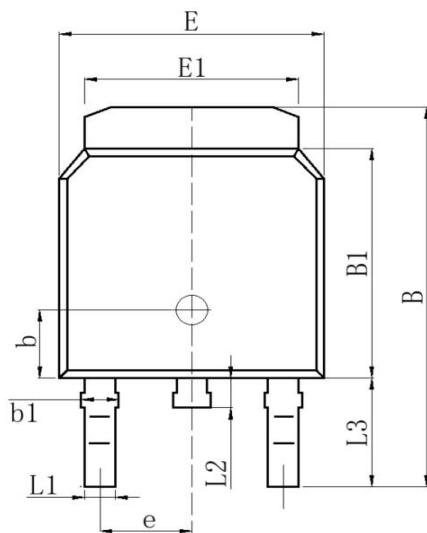
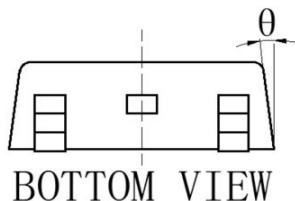


Figure 4: Diode Recovery Test Circuit & Waveform

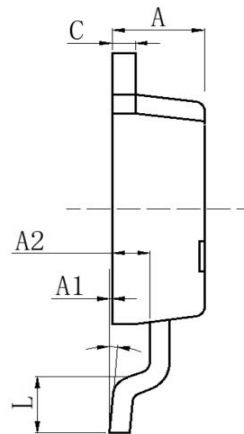
Package Mechanical Data(TO-252-3L)



FRONT VIEW



BOTTOM VIEW



SIDE VIEW

SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	—	0.10
A2	0.95	1.00	1.05
C	0.508REF		
L	1.40	1.50	1.60
E	6.50	6.60	6.70
E1	5.20	5.30	5.40
B	9.90	10.10	10.30
B1	6.00	6.10	6.20
b	1.70	1.80	1.90
b1	1.00MAX		
L1	0.60	0.75	0.90
L2	0.70	0.90	
L3	2.95REF		
e	2.286BSC		
θ	7°		

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